

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1302	Sep-96	9639 A3	ANAM, K.	DN624720ABA	0.8μ OX/NI (2 MTL)	08 SOIC 150

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Preconditioning (P/C):
HTC Vapor Phase
P-18405

<u>Electrical</u>	<u>Cum %</u>
233/0	0.0%

Infant / High Voltage Life
125°C, 6.0 V.
P-18430, P-18498

<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
231/0	77/0	77/0	82 Fits

*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0

Temp Cycle
-55°C to +125°C
P-18499

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
39/0	39/0	0.0%

Biased Moisture (HAST)
120°C/85% RH, 5.5 V.
P-18500

<u>100 Hr</u>	<u>Cum %</u>
77/0	0.0%

Autoclave
121°C/100% RH, 2 Atoms
P-18501

<u>96 Hr</u>	<u>Cum %</u>
38/0	0.0%

Failure Mode

Failure Analysis